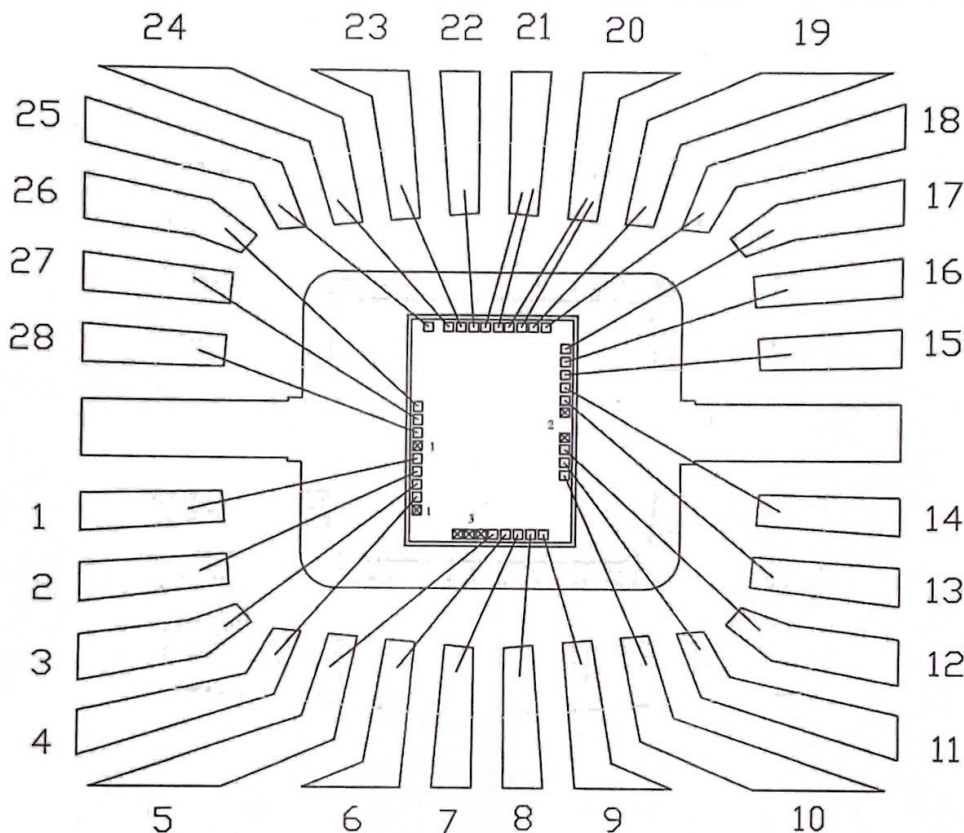


 池州华宇电子科技股份有限公司 CHIZHOU HISEMI ELECTRONICS TECHNOLOGY CO., LTD 焊线图纸 Bonding Diagram				客户代码 Customer No.	008	图号 Drawing No.	HY-PX-008-745 A	
产品名称 Product Type				HS26F2728TP		封装形式 PKG Type		SOP28L(6R)(300mil)
焊线种类 Wire Type	焊线直径(μm) Wire Diameter	焊线股数 NO. of wire	焊线总长(μm) Total wire length	最长线长(μm) Longest wire length	最短线长(μm) Shortest wire length	焊线材料号(绿色环保) Compound Type (Green)		LF线体尺寸 LF Pad Size
合金丝 Ag	20	30	50632	1907	1086	首选(Preferred): CEL-17021 HF 备选(Optional): EME-G630AY		SOP28L-6R (90°110mil) 2286*2794μm ²
客户图号 Customer drawing NO.								



封装传递方向 (翼片):
L/F Direction (D/A):

椭圆孔



封装图:
Chip photo:

特殊说明 Special Instructions:

DB注意:
1. 芯片居中放置;
WB注意:
1. 数字为不打线pad个数;

说明 Remarks	贴片胶类型 Epoxy type	芯片名称 Die name	芯片尺寸 Die Size	最小焊盘尺寸 Min BPZ (μm) ²	最小焊盘间距 Min BP Pitch (μm)	焊盘厚度(μm) Pad Thickness	焊盘下是否有电路 Circuit under Pad	划片道宽度 Sheet line (μm)	晶圆尺寸 Wafer Size	是否打线 If Wire-bond	减薄厚度 Grind Thickness
A座: DIE A	导电胶 (conductive) S210	HS5127	1610*1200(μm ²) 63.39*47.24(mil ²)	70*65	94	0.8	是/Yes	60	8	否/NO	300
B座: DIE B											
C座: DIE C											
编制 Prepared by	射漆 2024.4.18		制图日期 Create Date	2024/4/18		生效日期 Effective Date	客户确认签字/盖章: Customer Signature				
研发审核 R&D Check	无银 2024.4.18		产品工程审核 PEI Check			批准 Approved by	 2024.4.19				

*温馨提示: 图纸为产品下线生产的唯一依据, 请认真确认, 我司依据您签字后的图纸生产, 如因图纸错误会产生不可估量损失, 请知悉!

*warm tips: the drawing is the only basis for the production of the product. Please confirm it carefully. Our company will produce the drawings according to the drawings you have signed back, such as drawing mistakes, which will produce incalculable loss. Thank you

页码 Page

1/1